NO:RD-HK-080
Date:2011.12.14 R(REV:A2)

10/100 BASE-TX TRANSFORMERS

FOR AUTO MDI/MDIX APPLICATIONS

MODEL NO.: HK-080(Bottom epoxy)

FEATURE:

RoHS Compliant

RoHS peak solder rating 260℃/ 3~5 Sec

Do not use material and use that the prohibition that SS-00259 stipulates

Designed to meet IR requirement

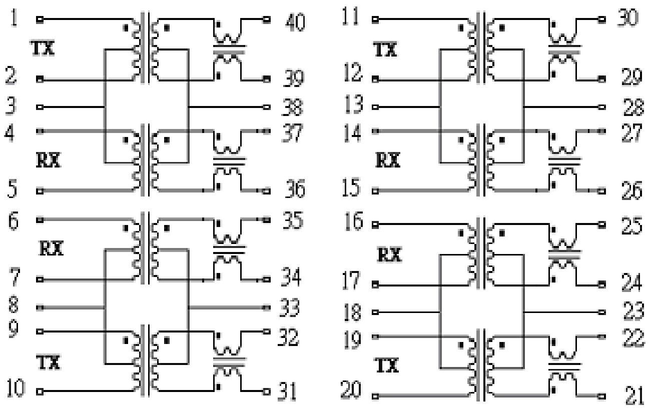
Specifications :At 25℃

Operating Temp -40℃ to + 85℃

Turns Ratio RX	**1CT : 1CT**
Turns Ratio TX	**1CT : 1CT**
OCL (Min)	**350 uH / 8mA**
Hi-pot	**1500VAC.**

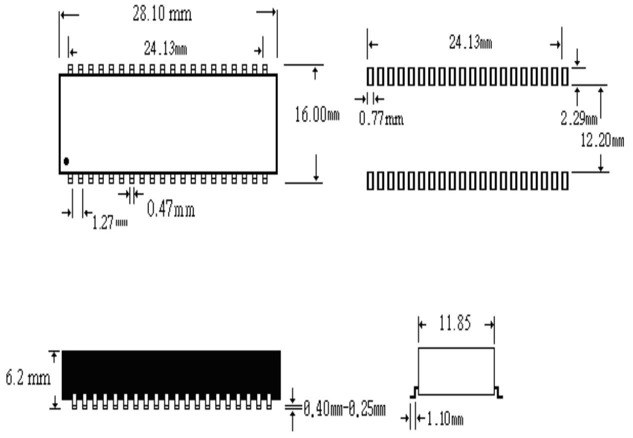
Parts Number	Insertion Loss (dB MAX) 0.1-100MHz	Return Loss (dB MIN)				Cross talk (dB MIN)				Differential to Common Mode Rejection (dB MIN)	
		2~30MHz	40MHz	50MHz	60~80MHz	1MHz	30MHz	60MHz	100MHZ	1~60MHz	60~200MHz
HK-080	-1.0	-18	-14.4	-13.1	-12	-55	-45	-40	-33	-37	-25

SCHEMATIC:

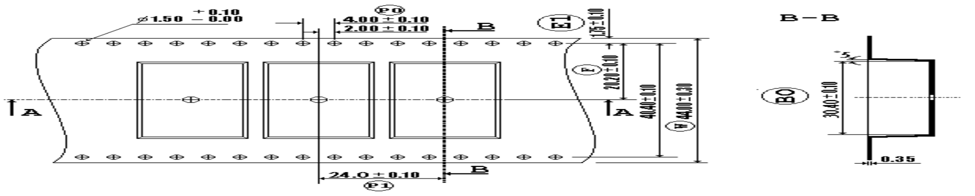


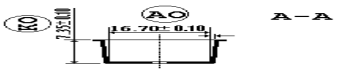
DIMENSION: mm

TOLERANCE:±0.25



Packing:





DIMENSION	W	A0	B0	K0	E	F
SPEC +/-	44.0 0.3	16.7 0.1	30.4 0.1	7.35 0.1	1.75 0.1	20.2 0.1
DIMENSION	P	P0	P2	D	D1	T
SPEC +/-	24.0 0.1	4.0 0.1	2.0 0.1	1.5 (MIN)	2.0 (MIN)	0.35 0.05

Tape & reel-----------350/reel
Tube-------------------16/tube

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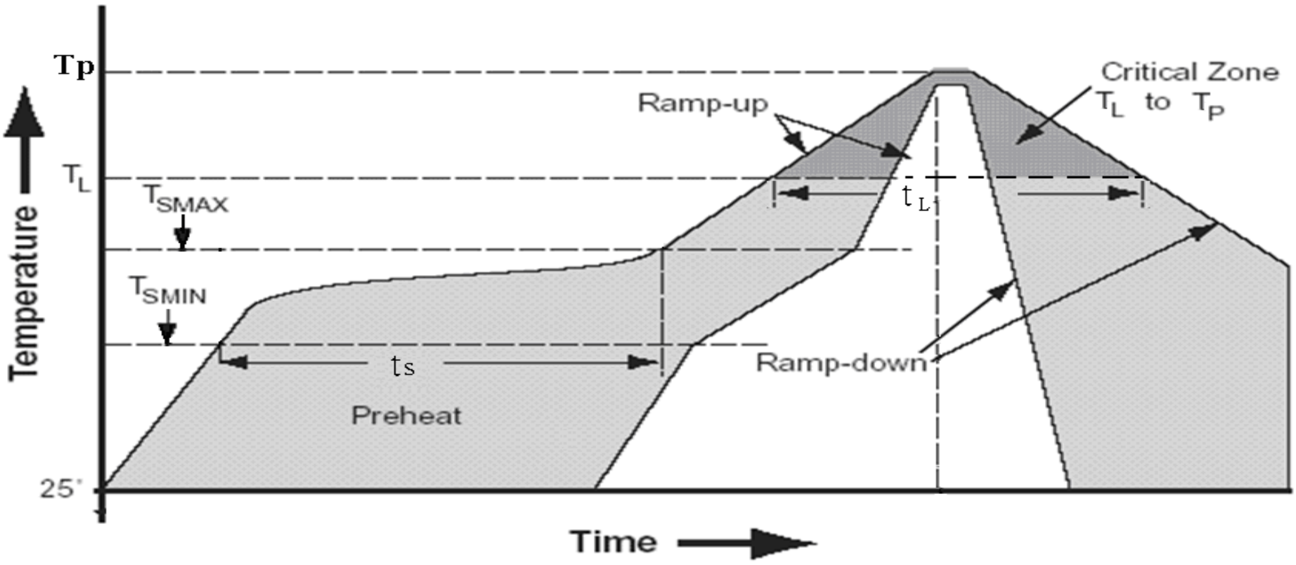
Solder Reflow profile for Lead-Free packages.

Package Peak Reflow Temperatures

Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate(T_L to T_P)	3℃ / Second Max.	
Preheat Temperature Min.(Ts min.) Temperature Max.(Ts max.) Time (min to max) (t_S)	150 ℃ 200 ℃ 60-180 sec	
Ts max. to T_L Ramp-up Rate	3℃ / Second Max.	
Time maintained above Temperature (T_L) Time (t_L)	217 ℃ 60-150 sec	
Peak Temperature (Tp) Time within 5 ℃ of actual peak Temp.	260 +0 / -5 ℃ 3 to 5 Sec	250 +0 / -5 ℃ 20 to 40 Sec
Ramp-down	6℃ / Second Max.	
Time 25 ℃ to Peak Temperature	8 minutes Max.	

Profile



MODEL NO.: HK-080

PACKING	
1.	**Tape & Reel：350pcs / Reel , 1750pcs / Carton**
2.	**Dry Pack：1pcs** **Product Description:(5g Silica Gel Desiccant)** **PH: 4-8** **Package Materials: Paper(Length 6.5±1cm , Width 5±1cm)**
3.	**Reel Packed By Vacuum**
4.	**Seal Per Jedec**